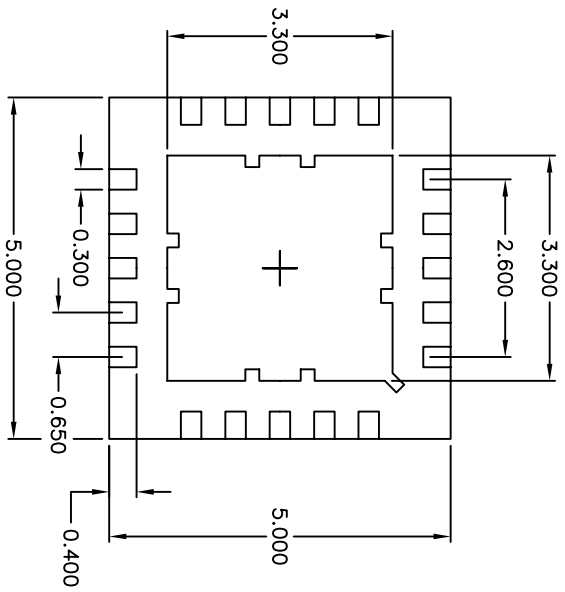
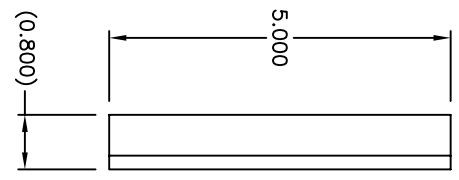
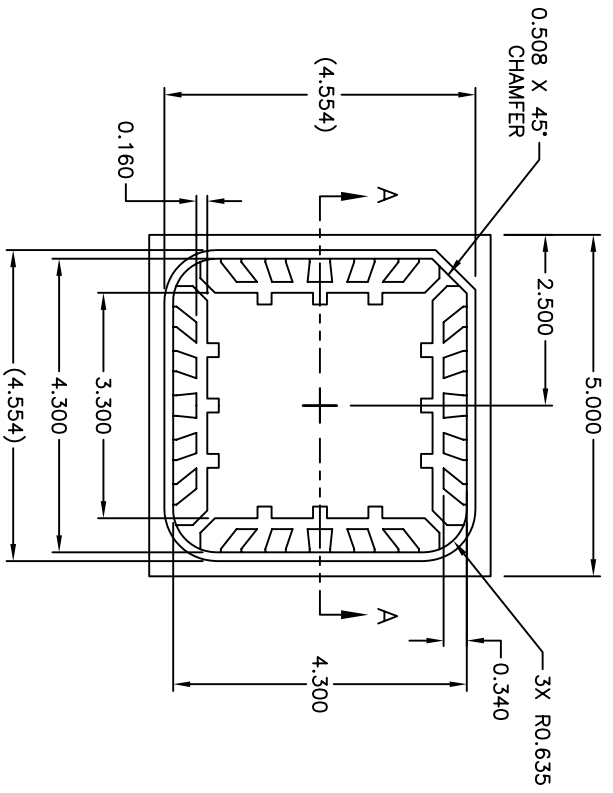


2

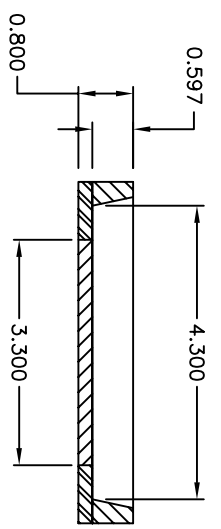
1

SEMPAC REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D.MORRIS
10658	11/03/06	PRODUCTION RELEASE	



TOP VIEW

BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ±.0076.
 5. DIE PAD: 3.300 X 3.300.
 6. JEDEC OUTLINE: MO-220 (VHHC-2).



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XXX ± 0.015 X.XXXX ± .1°

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	11/03/06
APP BY	P. FLASKERUD	DATE	11/03/06
CUSTOMER	----		

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION TO SEMPAK, INC. AND REPRODUCTION OR ISSUE IN ANY FORM IS NOT PERMITTED WITHOUT WRITTEN AUTHORITY FROM SEMPAK, INC.

SEMPAC, INC.
Open-Pak™ Technologies
www.sempac.com
588 E. WEDDELL DRIVE, SUITE 5
SUNNYVALE, CALIFORNIA 94089
PHONE: (408) 400-9002 FAX: (408) 400-9006

20 LEAD 5.00mm X 5.00mm
MLP Open-Pak

SIZE	PART NO.	REV
A	MLP5X5-20-OP-01	2
SCALE	NONE	
FILE	MLP5X5-20-OP-01-R2.DWG	
SHEET	1 OF 1	

2

1